



General Information

Series Style

Description

Features

RoHS

SMD Comm X8G HT150C Flex, Ceramic, 200 pF, 20%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0603, 0.4 mm

SMD Comm X8G HT150C Flex

SMD, MLCC, High Temperature,

High Temperature, Ultra-Stable

SMD Chip

Ultra-Stable

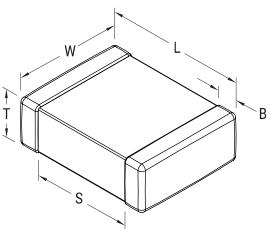
Flexible Termination

Yes

No No 4.6 mg 78 Weeks

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S		Termination Marking AEC-Q200 Typical Component Weight
Click here for	the 3D model.	Shelf Life
_		MSL
Dimensions		Specifications
Chip Size	0603	Capacitance
L	1.6mm +/-0.17mm	Measurement Condition

Cnip Size	0603
L	1.6mm +/-0.17mm
W	0.8mm +/-0.15mm
Т	0.8mm +/-0.15mm
S	0.4mm MIN
В	0.45mm +/-0.15mm

Packaging Specifications	
Packaging	T&R, 330mm, Paper Tape
Packaging Quantity	15000

MOL	•
Specifications	
Capacitance	200 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	20%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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